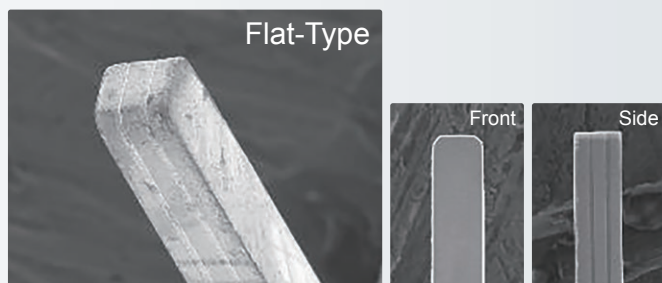
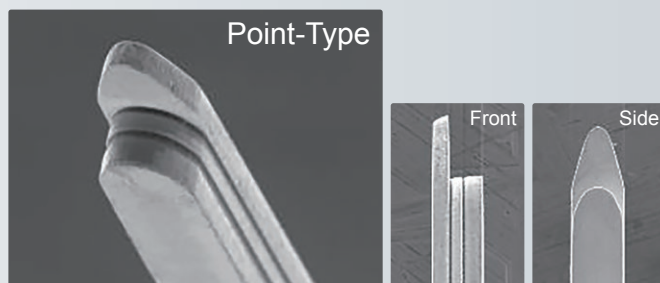


For printed circuit board and semiconductor package inspection system



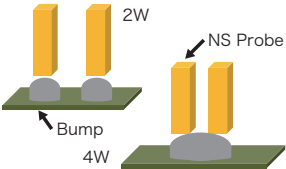
Good tolerance



Select the body metal

We developed the new probe that used MEMS process for min Pitch and possible to make various tip shape.

NS probe specifications

Probe Type	2W Pitch	4W Pitch	Tip Size	Force	Stroke	Raw Material	Contact Images
 Flat	55 μ m	Bump Pitch 100 μ m Probe Pitch 55 μ m	28 $\times$ 25 μ m	1.0gf	60 μ m	PdCo/Cu Isolation Coat Au Surface	
 Point	55 μ m	Bump Pitch 100 μ m Probe Pitch 35 μ m	28 $\times$ 25 μ m	1.0gf	60 μ m	PdCo/Cu Isolation Coat Au Surface	